

IN THE DRAWINGS

Pursuant to the Examiner's objections to the Drawings, an amended drawing sheet 2/2 is submitted as a replacement drawing sheet for the Figures 3a and 3b. Although the replacement drawing sheet includes the Figures 3a and 3b, as appearing on the immediate prior version of this sheet, only Figure 3b is being amended without adding any new subject matter. Reconsideration for the amended Figure 3b is respectfully requested. In the amended Figure 3b, a second solder bump is formed over a second absorption layer, wherein the first absorption layer and the second absorption layer are laterally isolated from each other by a spacing of approximately 1-100 μm . Support for this amendment to Figure 3b may be found in the Applicants' Specification on page 16, lines 4-7.

In the Office Action, the Examiner objected to the Specification on the basis that the specification allegedly failed to disclose a second solder bump formed over a second absorption layer, wherein the first absorption layer and the second absorption layer are laterally isolated from each other by a spacing of approximately 1-100 μm . Applicants respectfully disagree with this assertion because the concept of trenches having in the range of approximately 1 μm - 100 μm , separating adjacent solder bumps formed by adjacent absorption layers, is disclosed on page 16, lines 4-7 in the Applicants' Specification. Therefore, no changes are believed to be necessary in the detailed description of the Figure 3b. Accordingly, the Applicants respectfully submit that the objections to the Drawings and the Specification should be withdrawn.